US00D922546S

(12) **United States Design Patent** (10) **Patent No.: US D922,546 S**
Yoshida et al. (45) **Date of Patent: ** Jun. 15, 2021**

(54) **COMPOSITE SEAL MEMBER FOR SEMICONDUCTOR PRODUCTION APPARATUS**

(71) Applicant: **Valqua, Ltd.**, Tokyo (JP)

(72) Inventors: **Nobuhiro Yoshida**, Nara (JP); **Ippei Nakagawa**, Nara (JP); **Sangho Kim**, Gyeonggi-do (KR)

(73) Assignee: **Valqua, Ltd.**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/714,203**

(22) Filed: **Nov. 21, 2019**

Related U.S. Application Data

(62) Division of application No. 35/506,052, filed on May 14, 2018 (U.S. filing date under 35 U.S.C. 384), and having an international filing date of May 14, 2018, now Pat. No. Des. 898,170.

(30) **Foreign Application Priority Data**

Dec. 1, 2017 (JP) 2017026882
Dec. 1, 2017 (JP) 2017026887
Feb. 8, 2018 (JP) 2018002528

(51) **LOC (13) Cl.** **23-01**

(52) **U.S. Cl.**
USPC **D23/269**
CPC ***F16J 15/025*** (2013.01)

(58) **Field of Classification Search**
USPC D15/7, 9, 11, 17, 21, 28, 123, 199; D23/269, 386, 259; D8/349; 277/602–626; 285/95, 109, 336, 910, 918
CPC F16K 51/02; F16J 15/025; F16J 15/0887; F16J 15/104; F16J 15/128
See application file for complete search history.

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Primary Examiner — Richard E Chilcot

(74) *Attorney, Agent, or Firm* — The Webb Law Firm

(57) **CLAIM**

The ornamental design for a composite seal member for semiconductor production apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a composite seal member for semiconductor production apparatus, showing our new design;
FIG. **2** is a front elevation view thereof;
FIG. **3** is a rear elevation view thereof;
FIG. **4** is a left side elevation view thereof;
FIG. **5** is a right side elevation view thereof;
FIG. **6** is a top view thereof;
FIG. **7** is a bottom view thereof;
FIG. **8** is a cross-sectional view thereof; and,

(Continued)

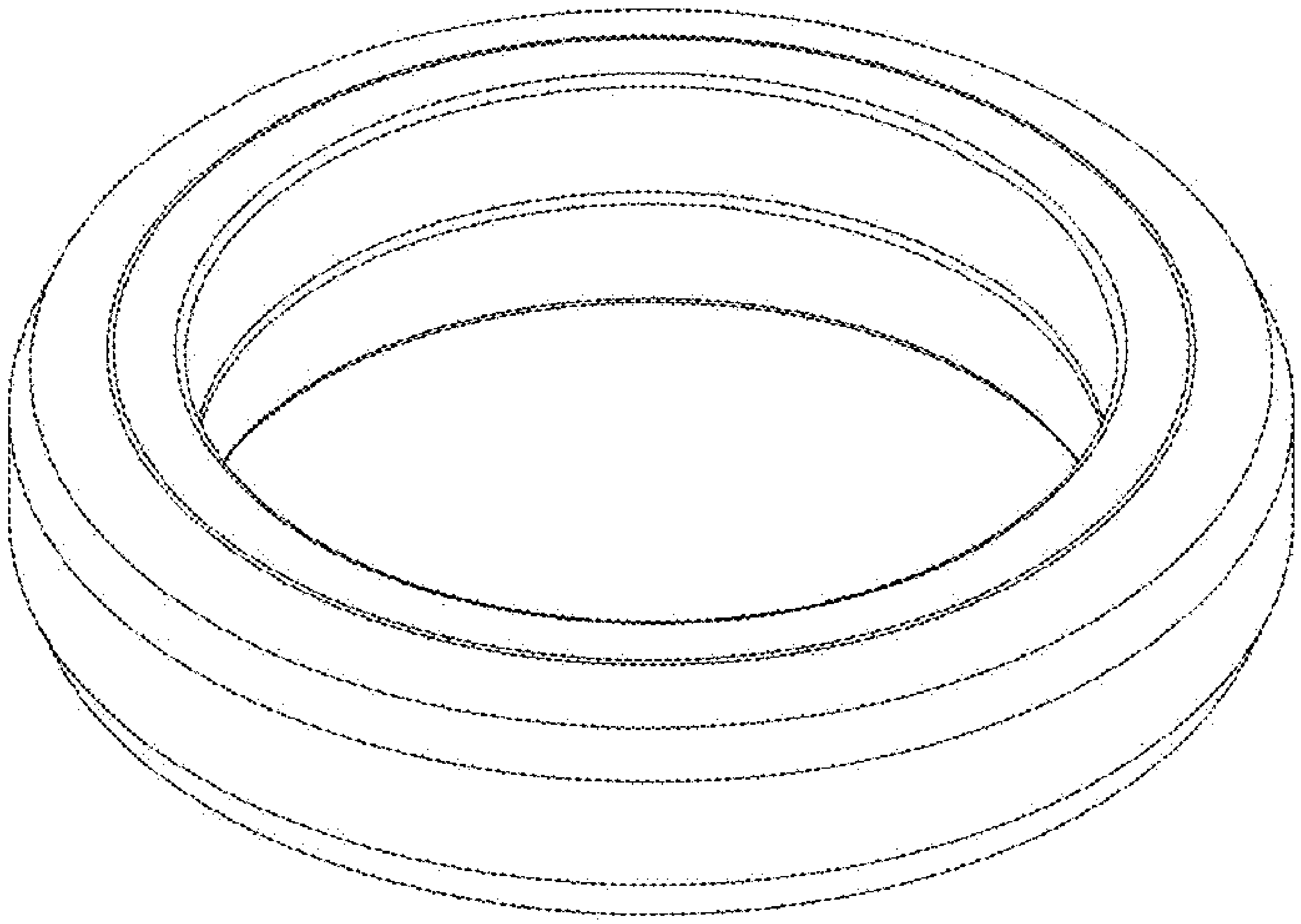

FIG. **9** is an enlarged cross-sectional view of a portion thereof.

1 Claim, 9 Drawing Sheets

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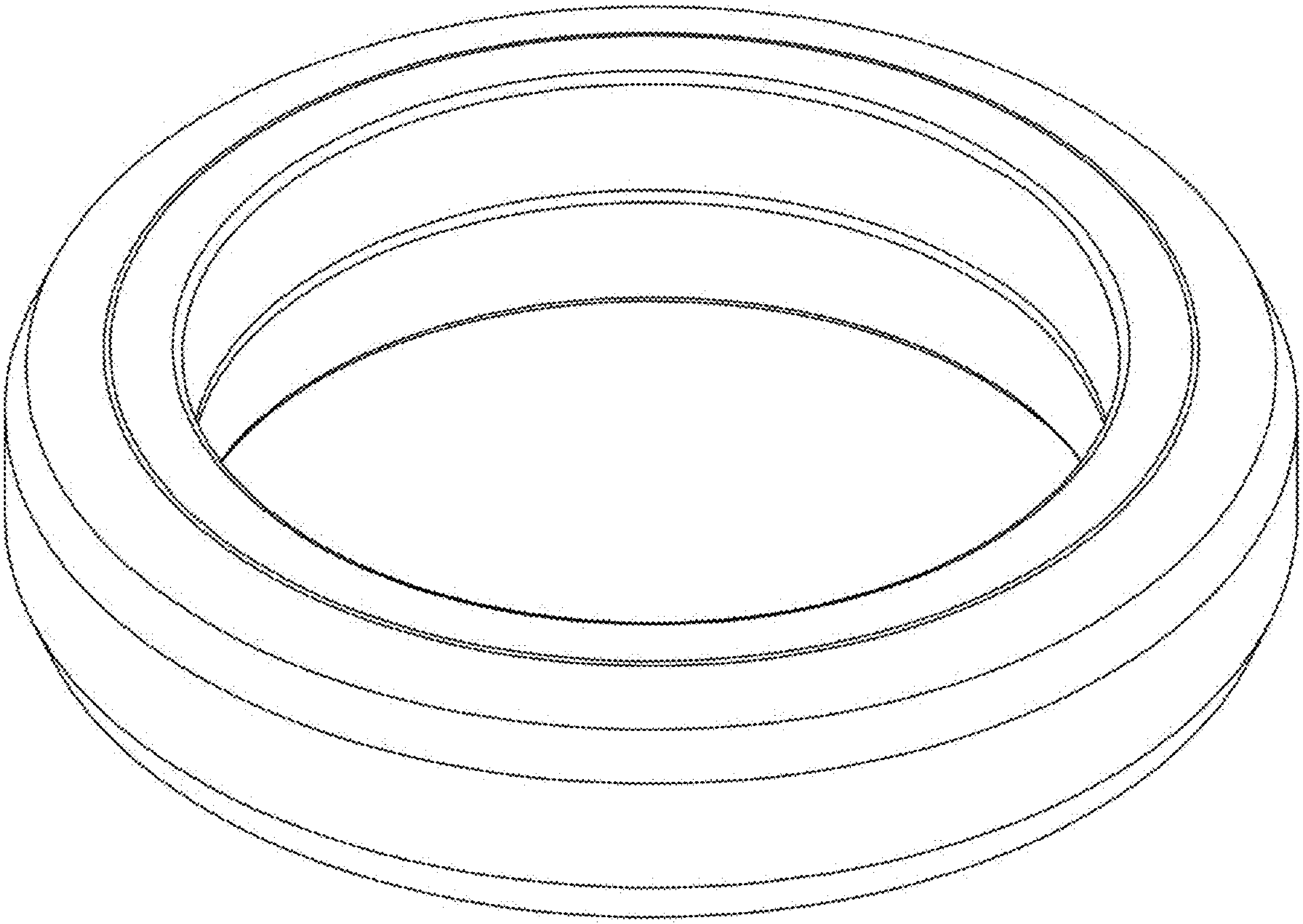

FIG. 1

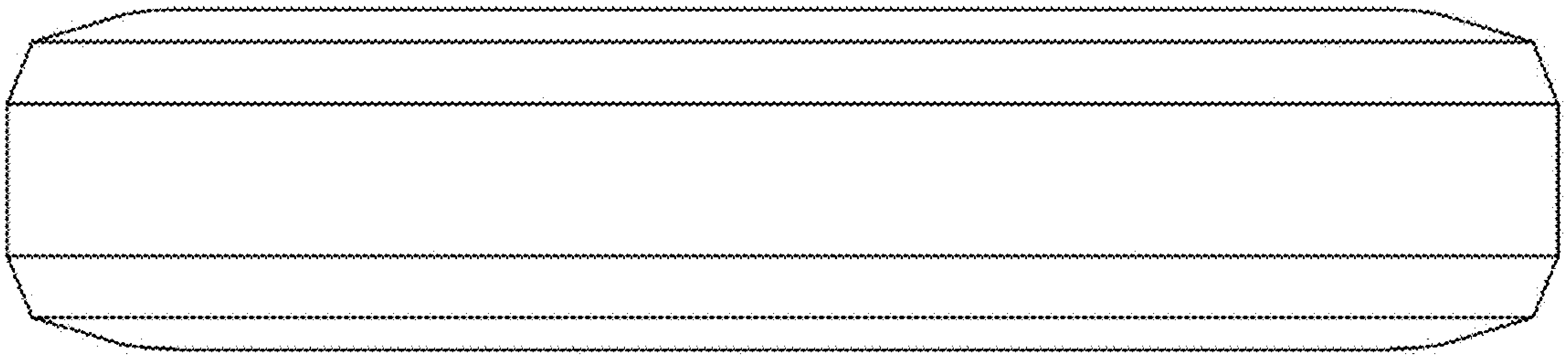

FIG. 2

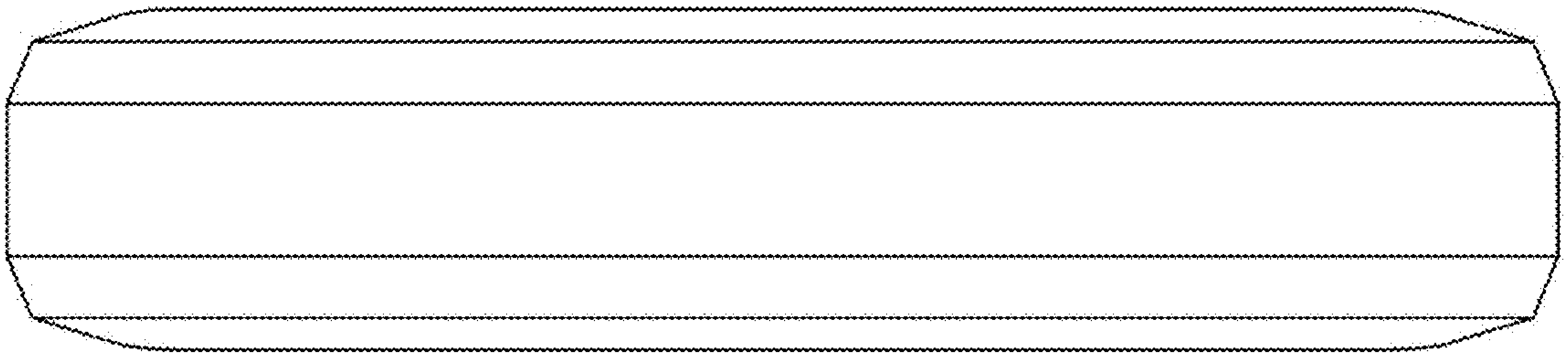

FIG. 3

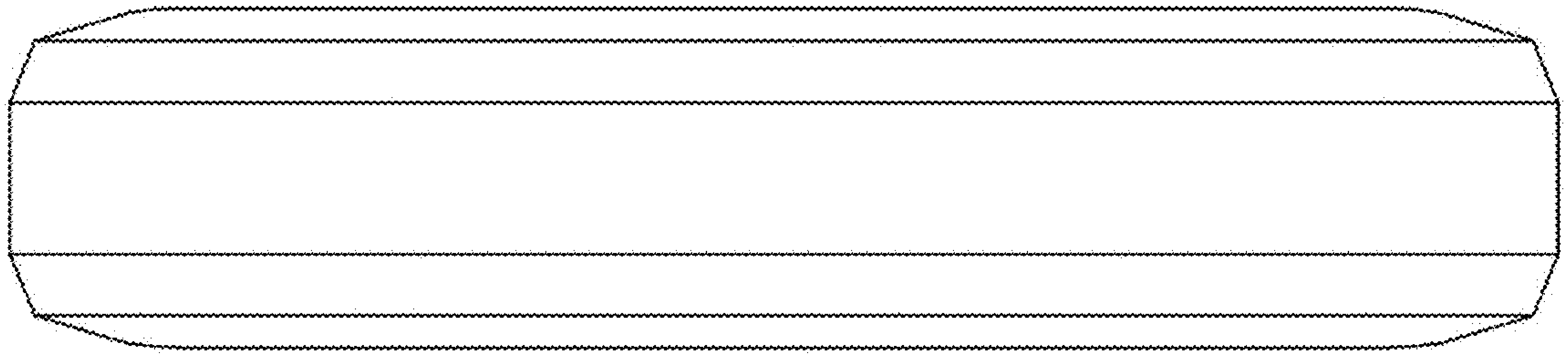

FIG. 4

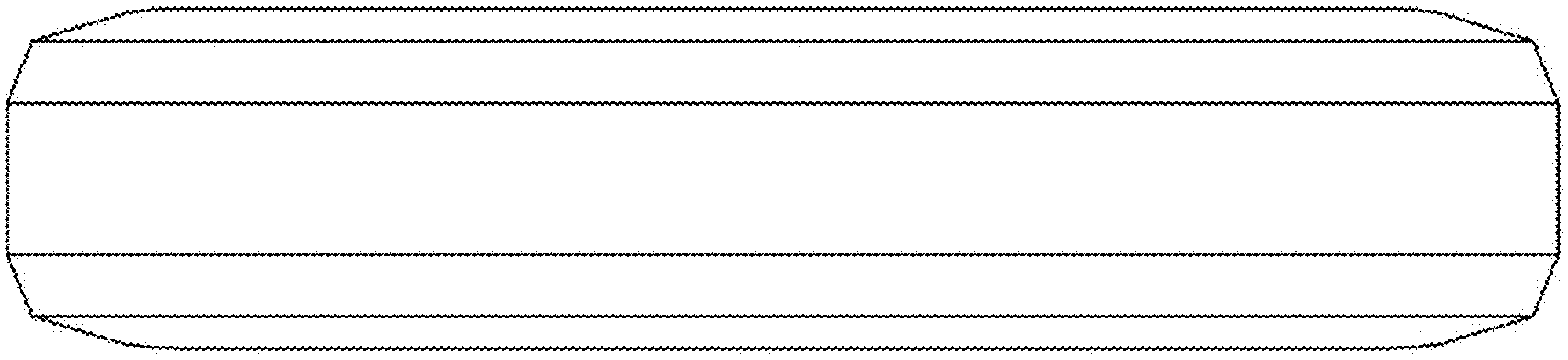

FIG. 5

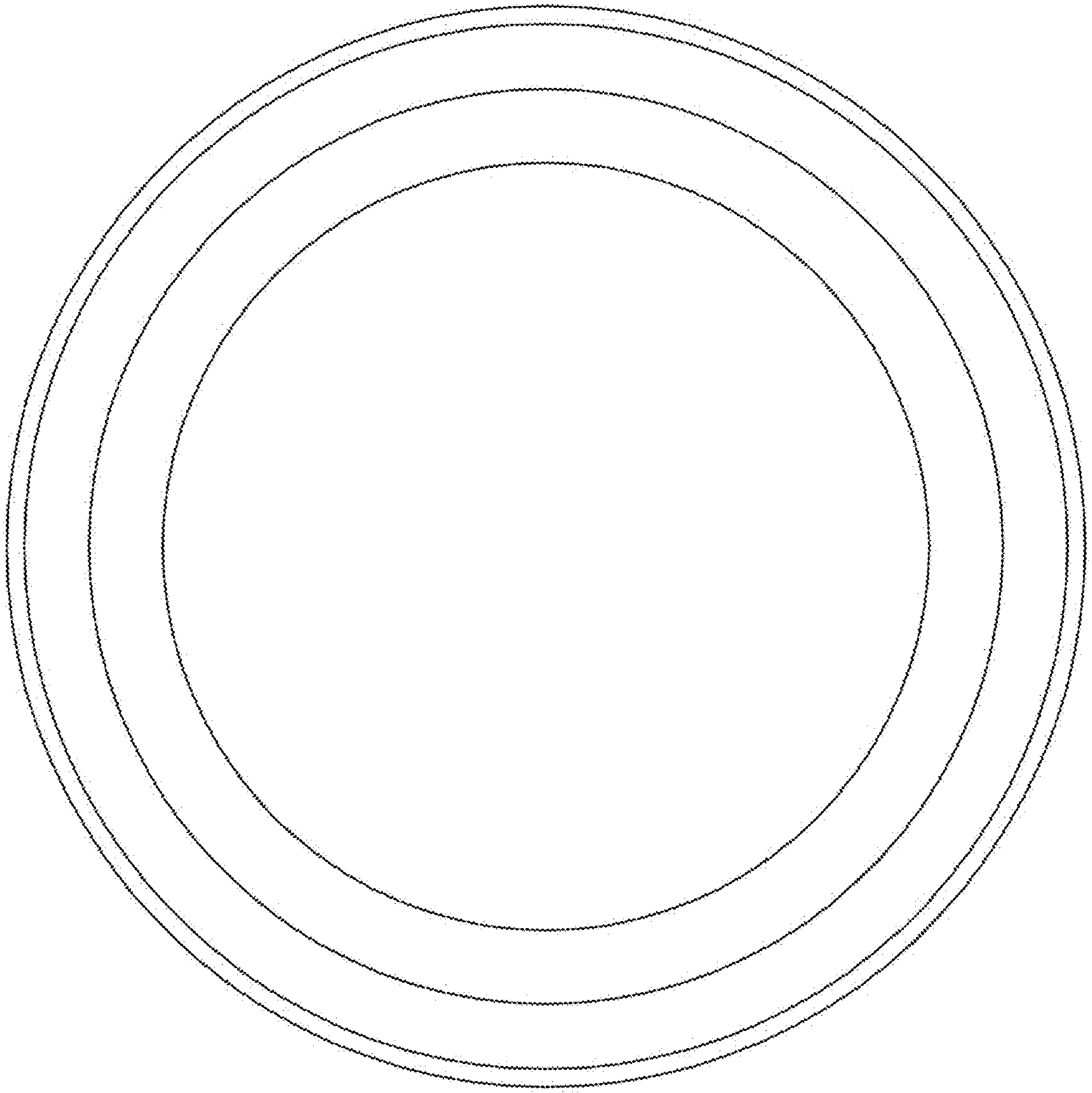

FIG. 6

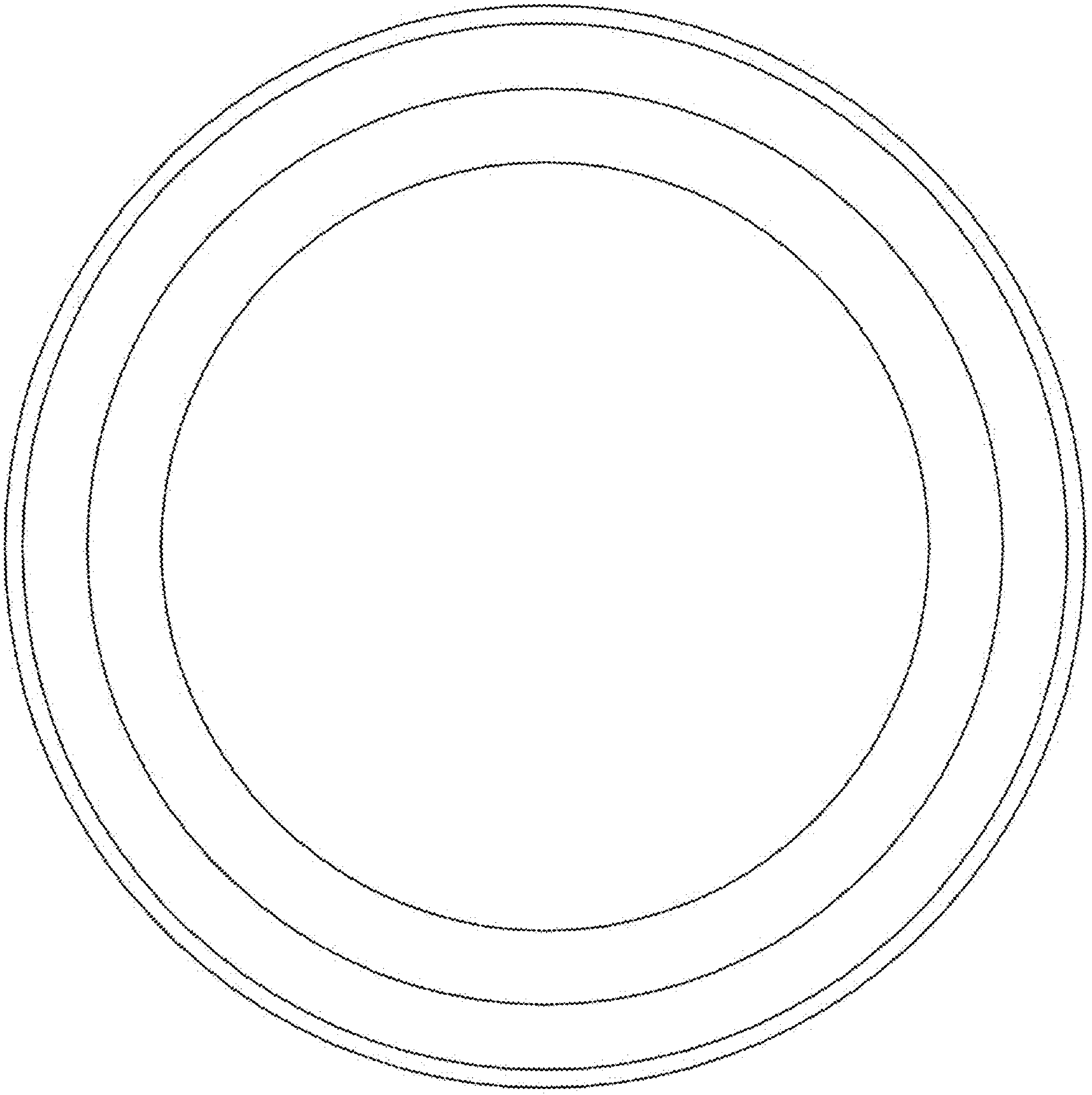

FIG. 7

FIG. 8

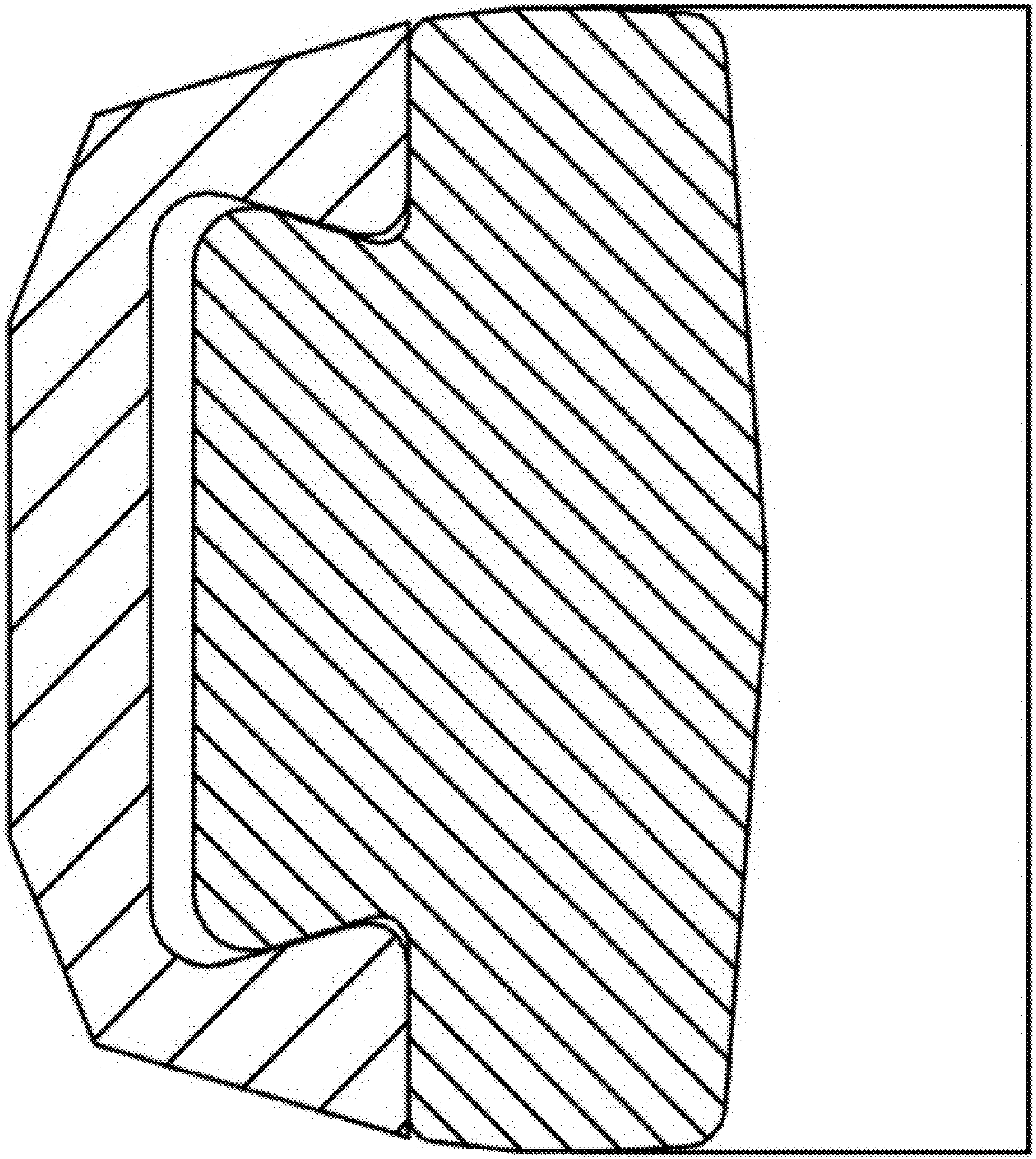

FIG. 9